



Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1809-02**                      Date: September 26, 2018  
Product Affected: SSOP-20, 28  
(Refer to attachment 2 for affected part numbers)

MEANS OF DISTINGUISHING CHANGED DEVICES:  
 Product Mark  
 Back Mark                      Lot # will have a "MM" prefix  
 Date Code  
 Other

Date Effective: December 26, 2018

Contact: IDT PCN DESK

Attachment:                       Yes                       No

E-mail: [pcndesk@idt.com](mailto:pcndesk@idt.com)

Samples:                      Please contact your local sales representative for sample request & availability.

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

This notification is to advise our customers that IDT is adding Carsem (M-site), Malaysia as an alternate assembly facility.

There is no change to the moisture performance rating.

Please refer to Attachment 1 for the qualification summary and material set details.  
Please refer to Attachment 2 for affected part# list.

**RELIABILITY/QUALIFICATION SUMMARY:**

Qualification has been successfully completed. There is no change in MSL rating.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.  
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_                       *Approval for shipments prior to effective date.*

Name/Date: \_\_\_\_\_                      E-Mail Address: \_\_\_\_\_

Title: \_\_\_\_\_                      Phone# /Fax# : \_\_\_\_\_

**CUSTOMER COMMENTS:**

\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_                      DATE \_\_\_\_\_



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**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

**ATTACHMENT 1 - PCN # : A1809-02**

**PCN Type:** Alternate Assembly Location & Change of material sets

**Data Sheet Change:** N/A

**Detail Of Change:**

This notification is to advise our customers that IDT is adding Carsem (M site), Malaysia as an alternate assembly facility.

The material set details of the current and alternate Assembly location are shown in the tables below. The die attach, mold compound and bonding wire used at the alternate assembly site are qualified IDT materials. There is no change from the existing qualified lead frame material and lead finish for this alternate assembly site.

SSOP - Qualified Material Sets, by Assembly Subcontractor

	Existing	Alternate
Material Set / Assembly	ATP - Amkor, Philippines	CRSM - Carsem, Malaysia
Die Attach	Ablestik 8290	QMI519
Bonding Wire	Gold wire & Copper wire	Gold wire & Copper wire
Mold Compound	EME-G600	CEL8240HF10LXC



**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

**ATTACHMENT 1 - PCN # : A1809-02**

**Qualification Information and Qualification Data:**

**Affected Packages:** SSOP-20, 28

**Assembly Material:** The affected package type is using the respective subcon standard materials as shown on page 1 of this attachment. Qualification testing was completed on the worse case package.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests

**Qualification Vehicle:** SSOP-28 (3 lots Gold Wire & 3 lots Copper Wire)

Test Description	Test Method	Test Results (Rej / SS)					
		Gold Wire			Copper Wire		
		Lot 1	Lot 2	Lot 3	Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/5	0/5	0/5	0/5
Bond Pull Test	IDT Spec MAC-3010	0/5	0/5	0/5	0/5	0/5	0/5
X Ray	IDT Spec. MAC-3012	0/45	0/45	0/45	0/45	0/45	0/45
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	0/25	0/25	0/25	0/25

\* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



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## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT 2 - PCN # : A1809-02

#### Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
49FCT20805PYGI	49FCT805APYGI	74FCT245CTPYG	74FCT3807EPYGI8
49FCT20805PYGI8	49FCT805APYGI8	74FCT245CTPYG8	74FCT3807PYG
49FCT3805APYG	49FCT805CTPYG	74FCT3244APYG	74FCT3807PYG8
49FCT3805APYG8	49FCT805CTPYG8	74FCT3244APYG8	74FCT3807PYGI
49FCT3805APYGI	49FCT805PYG	74FCT3244PYG	74FCT3807PYGI8
49FCT3805APYGI8	49FCT805PYG8	74FCT3244PYG8	74FCT3807SPYGI
49FCT3805BPYG	49FCT805PYGI	74FCT373ATPYG	74FCT3807SPYGI8
49FCT3805BPYG8	49FCT805PYGI8	74FCT373ATPYG8	74FCT3811PYGI
49FCT3805BPYGI	74FCT20807PYGI	74FCT373CTPYG	74FCT3811PYGI8
49FCT3805BPYGI8	74FCT20807PYGI8	74FCT373CTPYG8	8T33FS314PYGI
49FCT3805DPYGI	74FCT240ATPYG	74FCT3807APYG	8T33FS314PYGI8
49FCT3805DPYGI8	74FCT240ATPYG8	74FCT3807APYG8	9DB633AFILF
49FCT3805EPYGI	74FCT240CTPYG	74FCT3807APYGI	9DB633AFILFT
49FCT3805EPYGI8	74FCT240CTPYG8	74FCT3807APYGI8	9DB633AFLF
49FCT3805PYG	74FCT244ATPYG	74FCT3807DPYGI	9DB633AFLFT
49FCT3805PYG8	74FCT244ATPYG8	74FCT3807DPYGI5	LDS6107PYGI
49FCT3805PYGI	74FCT244CTPYG	74FCT3807DPYGI8	LDS6107PYGI8
49FCT3805PYGI8	74FCT244CTPYG8	74FCT3807EPYG	LV810FILF
49FCT805APYG	74FCT245ATPYG	74FCT3807EPYG8	LV810FILFT
49FCT805APYG8	74FCT245ATPYG8	74FCT3807EPYGI	